

Amendments to the Specification:

Please replace paragraph [0014] with the following amended paragraph:

[0014] In the next step, illustrated in FIG. 1c, deposition of an “intermediate layer” of Cu alloy 118 has begun. This intermediate layer 118 is deposited by an electroplating process generally referred to as ECP. It is desired that this intermediate layer 118 be composed of a relatively high level of dopant (e.g. ~~Sn~~ or tin) mixed with the Cu. This dopant element would generally be chosen to have a lower reduction potential than Cu.